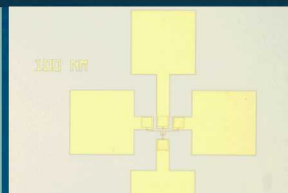
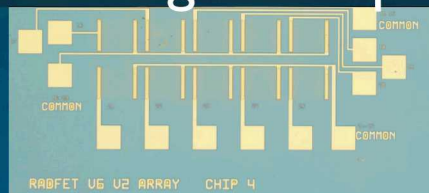


This paper describes objective technical results and analysis. Any subjective views or opinions that might be expressed in the paper do not necessarily represent the views of the U.S. Department of Energy or the United States Government.

SAND2019-9916C

The Deeply Depleted Graphene-Insulator-Semiconductor Junction:

A versatile approach towards light sensing across the electromagnetic spectrum



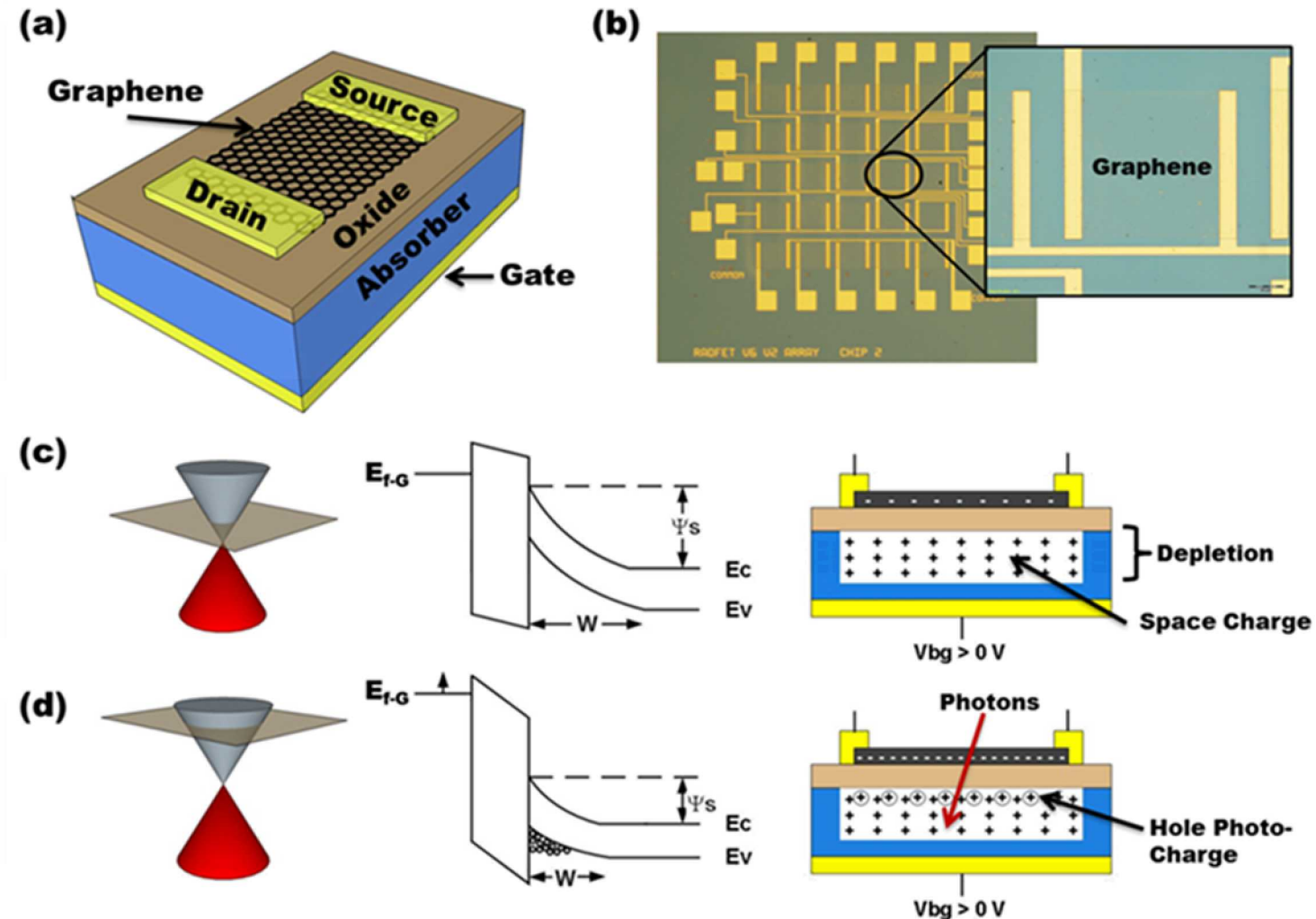
PRESENTED BY

Isaac Ruiz, Michael D. Goldflam, Raktim Sarma, Thomas E. Beechem III & Stephen W. Howell

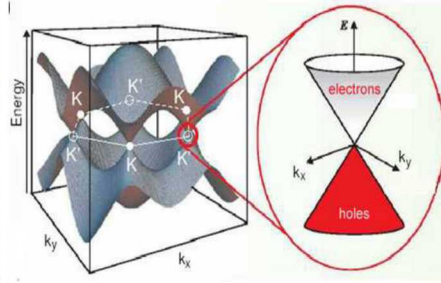
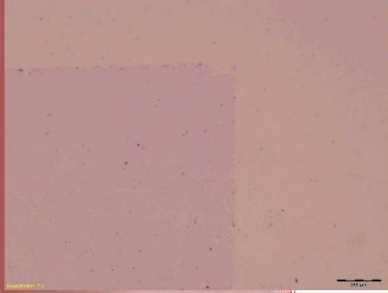


Sandia National Laboratories is a multimission laboratory managed and operated by National Technology & Engineering Solutions of Sandia, LLC, a wholly owned subsidiary of Honeywell International Inc., for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-NA0003525.

- Motivation
- Background of the D²GOS Junction Detector
 - Operating Principles
 - Operational Modes
- Optimization of the D²GOS Junction
 - Reducing interface states
 - Increased Well Lifetime
 - High Responsivity
- Detection in the NIR to Mid IR
 - InGaAs Device Demonstration
 - InAs Device Demonstration
- Detection of Gamma Radiation using a Si based D²GOS junction



Novel 2D Material



- Ultra-High Mobility
- Broadband Optical Absorption
- Tunable Electronic/Optical Properties
- Scalable
- Many demonstrations of sensing across EM spectrum (UV to IR)

Major Issues

- **Poor Absorber of Light**
 - Atomically thin
 - Low absorption
 - Short recombination length



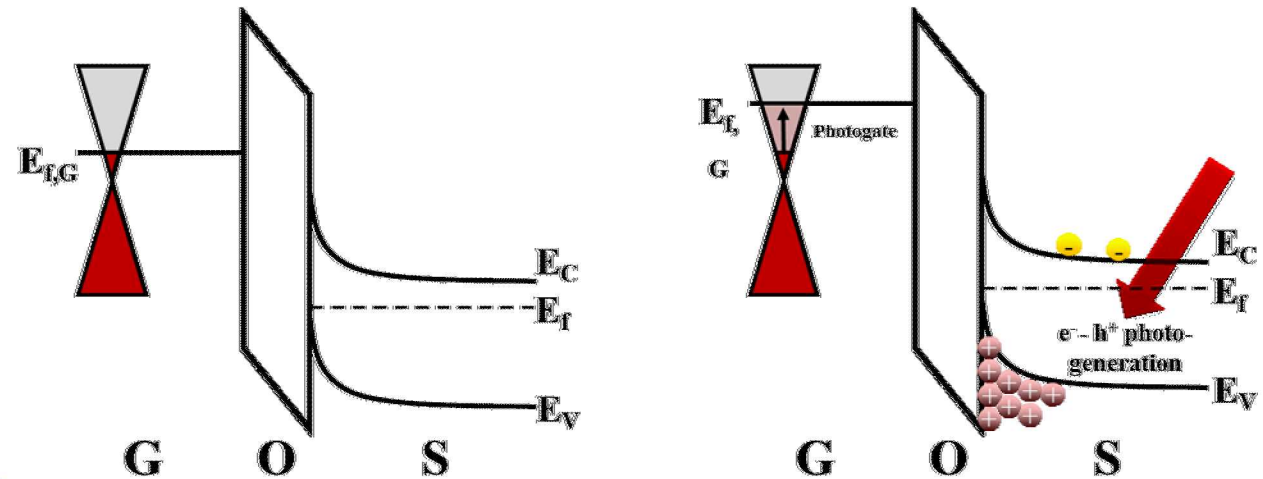
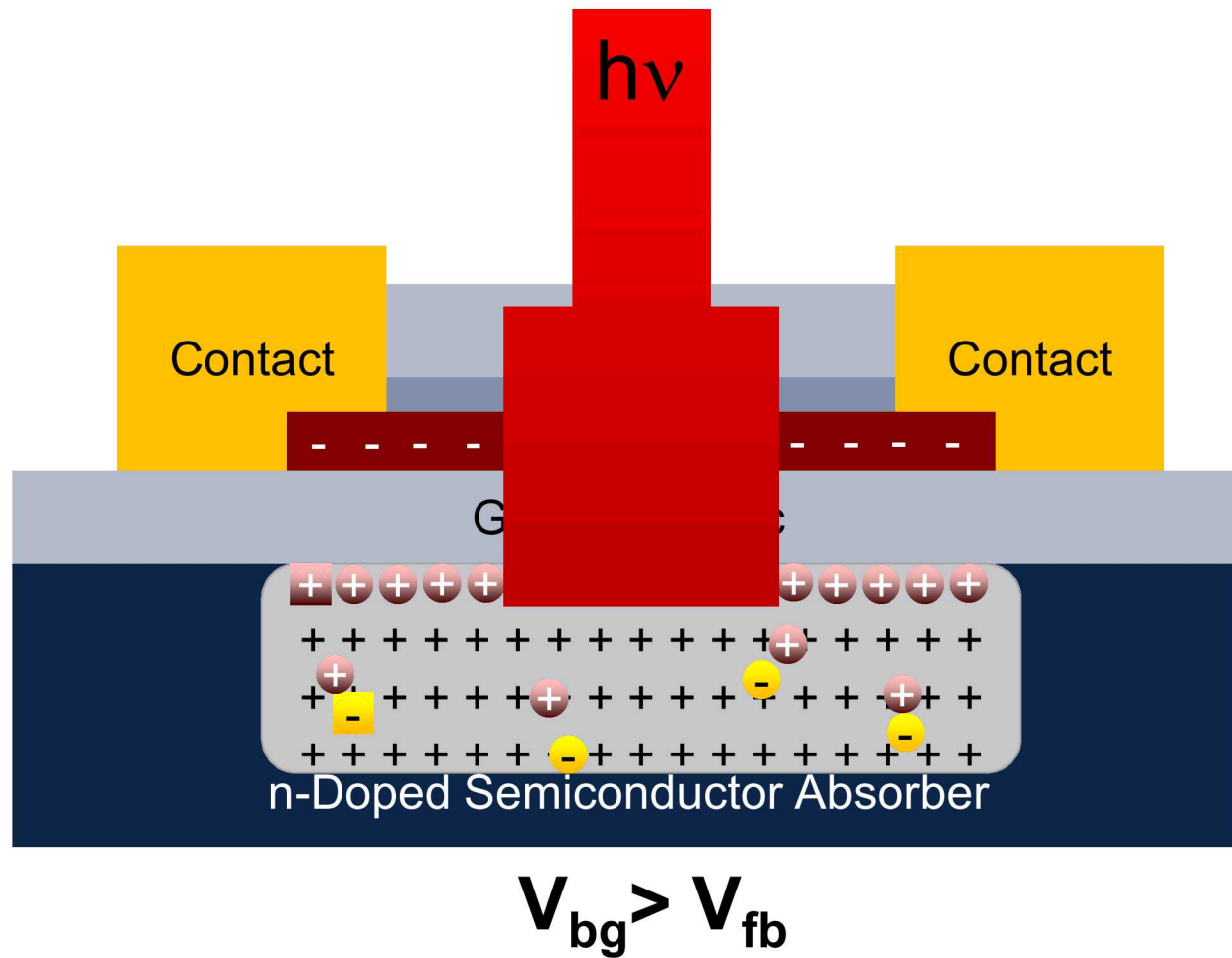
Solution:

Don't Absorb into the Graphene

Use graphene a to sense photo-generated generating in a **good** absorber.

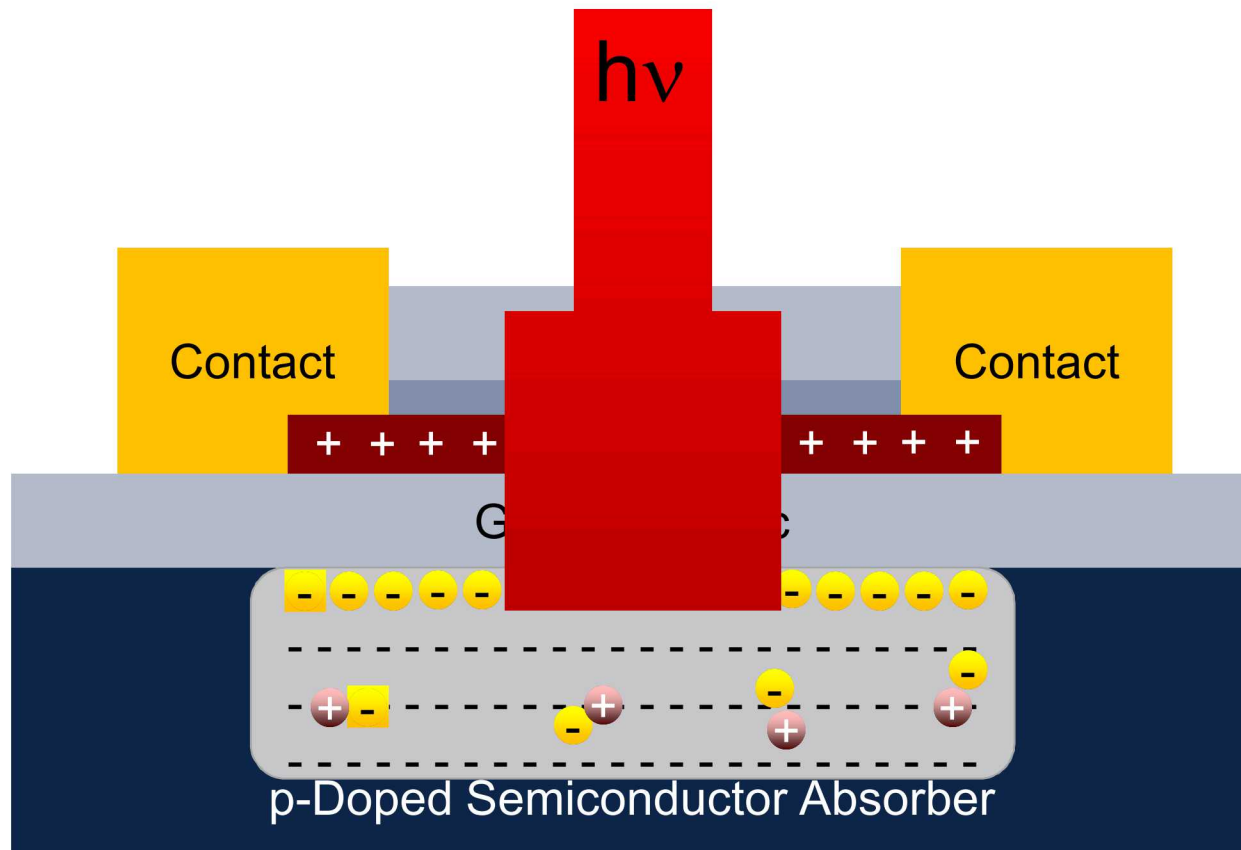
Operating Principle Graphene-Oxide Semiconductor Junction

1. Absorber-Oxide-Graphene Junction.
2. Low doped absorber is depleted with an applied back gate voltage.
3. Incoming light creates photo-generated charge in absorber.
4. Built in electric field separates electron-hole pairs.
5. Charge accumulates at semiconductor/Oxide interface.
6. Opposite charge is induced in the graphene channel, which can now be readout directly.

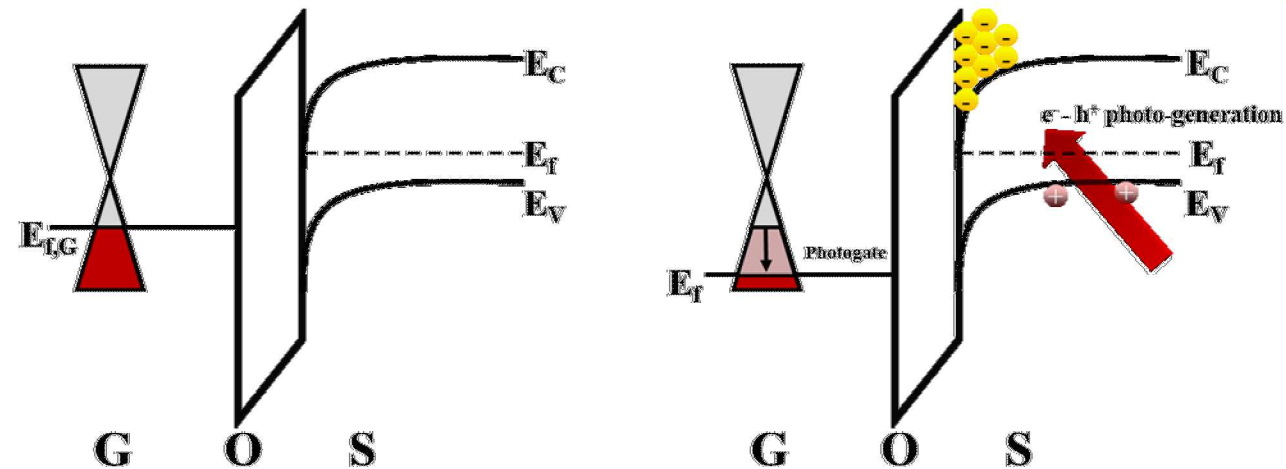


Operating Principle Graphene-Oxide Semiconductor Junction

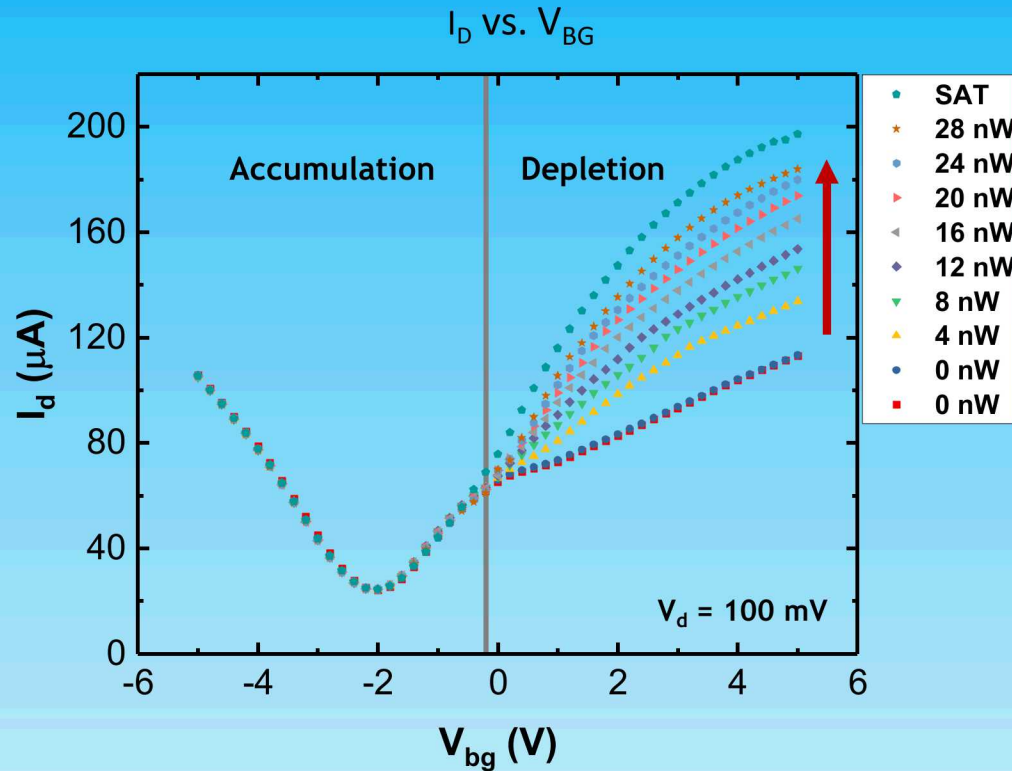
1. Absorber-Oxide-Graphene Junction.
2. Low doped absorber is depleted with an applied back gate voltage.
3. Incoming light creates photo-generated charge in absorber.
4. Built in electric field separates electron-hole pairs.
5. Charge accumulates at semiconductor/Oxide interface.
6. Opposite charge is induced in the graphene channel, which can now be readout directly.



$$V_{bg} < V_{fb}$$



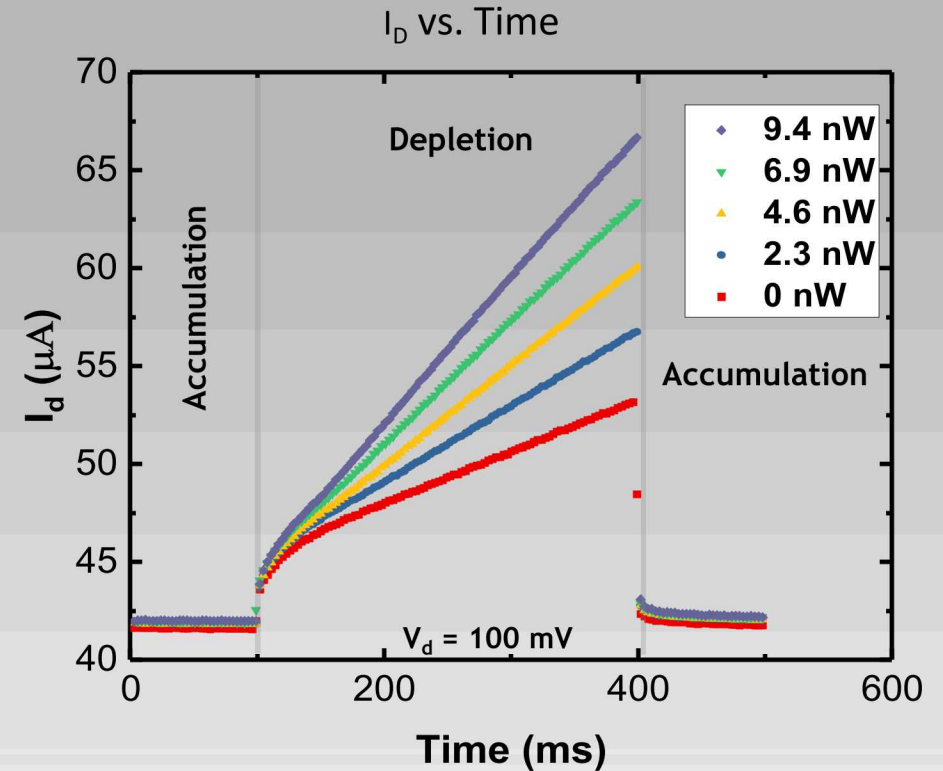
Device Characterization Mode



This mode allows for the GOS stack characterization of:

- Graphene's material properties
 - Doping, Mobility and Resistivity.
- Semiconductor material properties
 - Doping polarity and Band Gap
- GOS Junction V_{FB}
- Any induced damage from high energy events.

Detection Mode



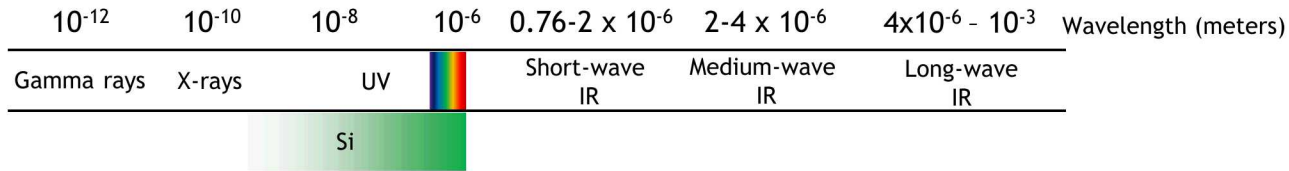
This mode allows for real time detection of light.

- Similar CCD (no charge shuttling).
- Integration of photo-induced charge.

This mode also allows for the characterization of thermally generated charge in the semiconductor.

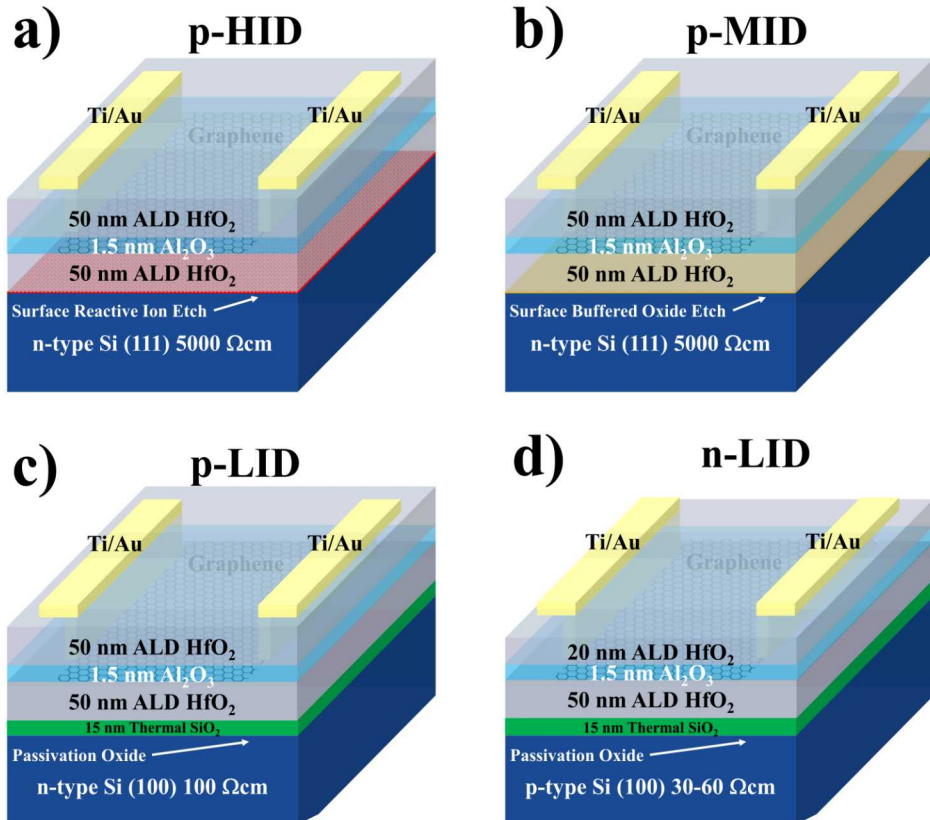
- Primarily Semiconductor/Oxide interface defect density.

Semiconductor/Oxide Interface on D²GOS Junctions in the Visible (635 nm)



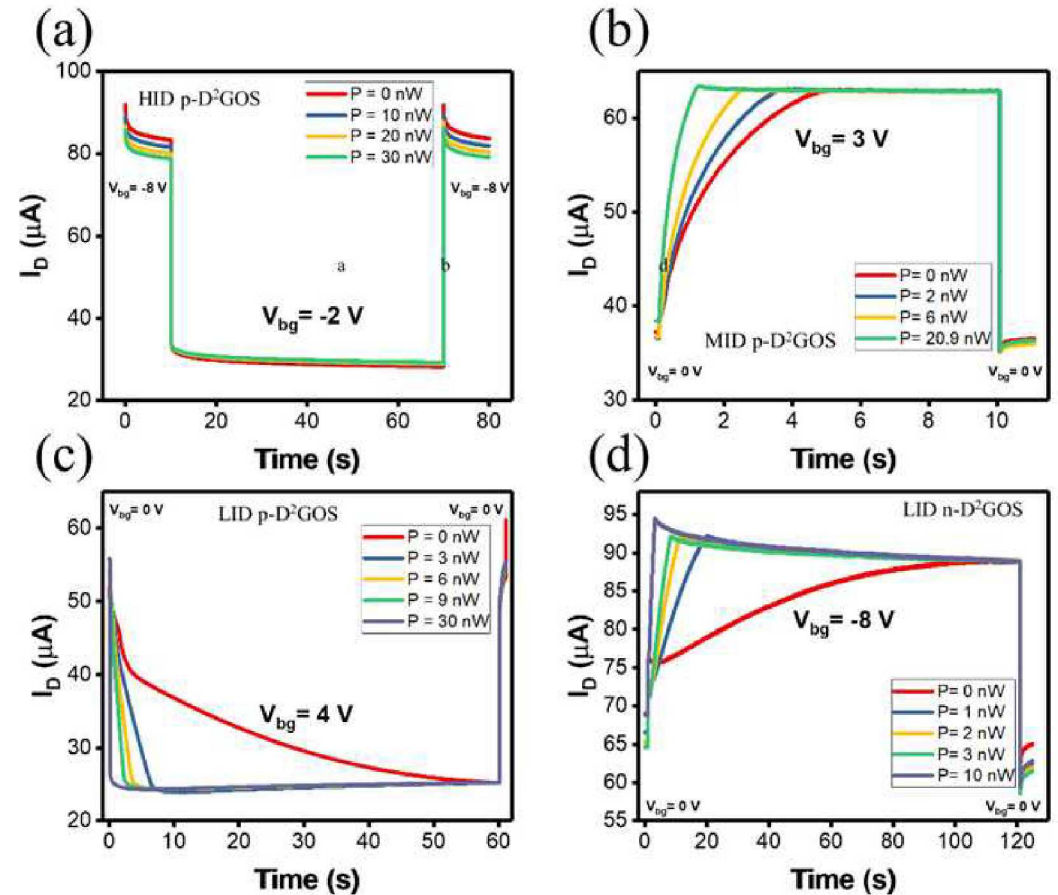
Question:

What happens if we minimize the interface states?



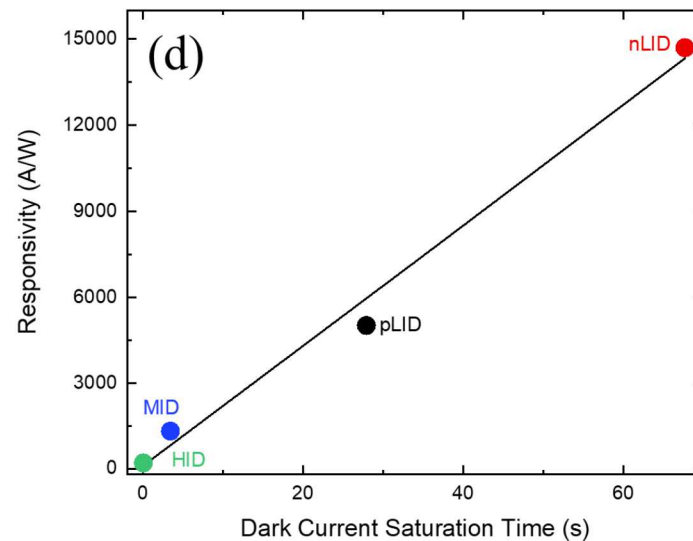
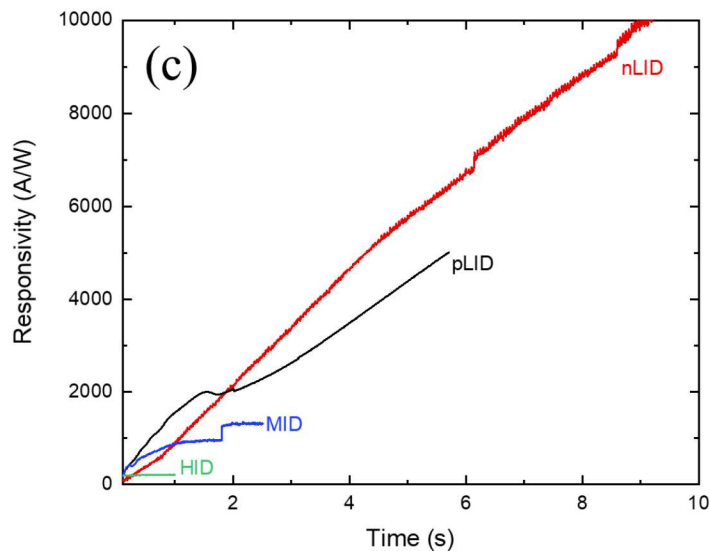
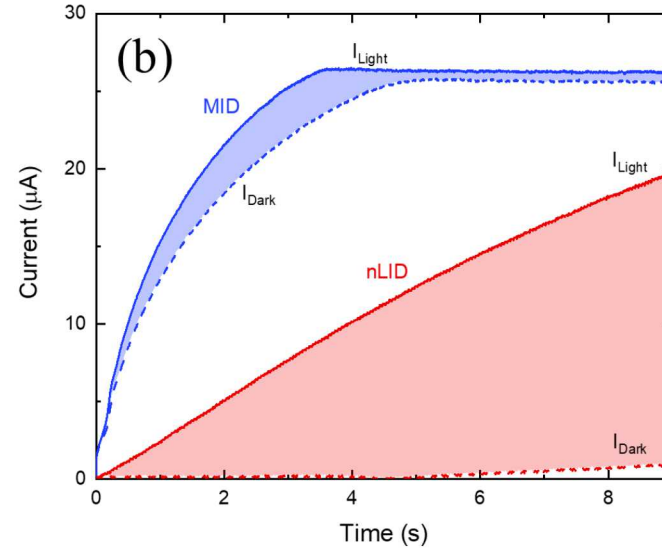
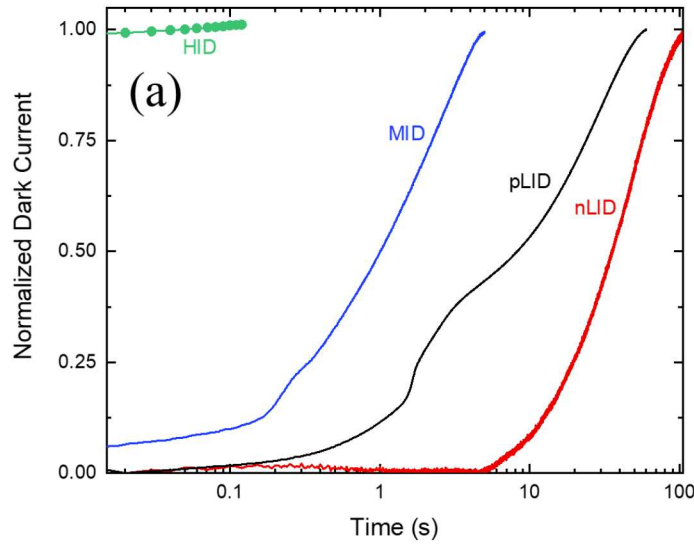
Answer:

Reduction in Interface defect density increases dark well lifetime from 6 seconds to 120 sec!



Variable Interface Defect D²GOS Junction Performance

Room Temperature Characterization



High interface defect GOS junction is not functional

Low Interface defect GOS junction has much lower dark current

Surface charge generation is the primary source of dark charge

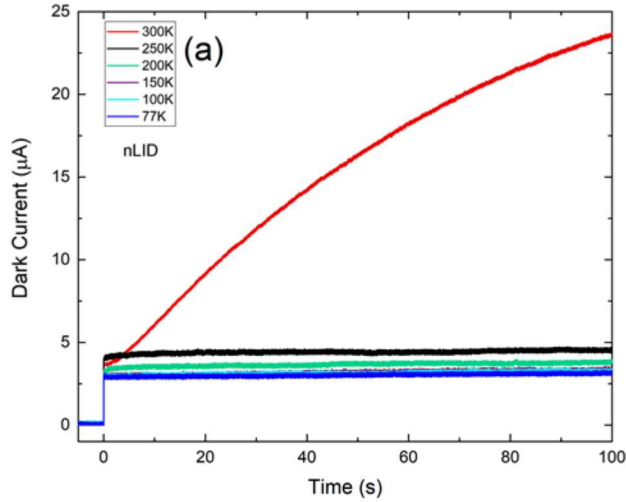
Responsivity is proportional to dark current saturation time.

Responsivity is also a highly dependent on the graphene mobility.

Low Temperature D²GOS Junction Performance (Visible and 635 nm)

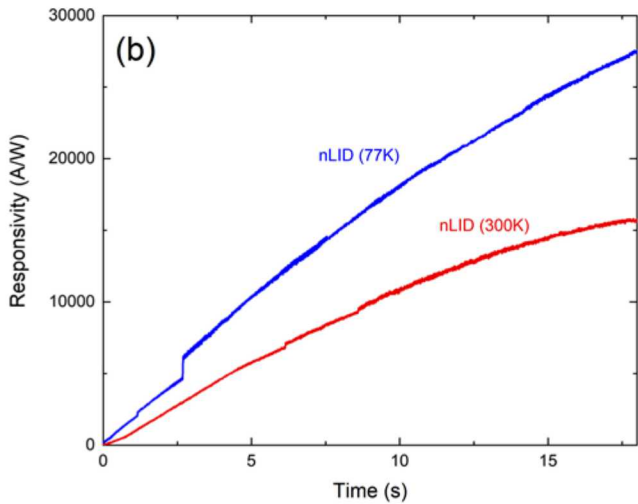


Low Temperature Characterization



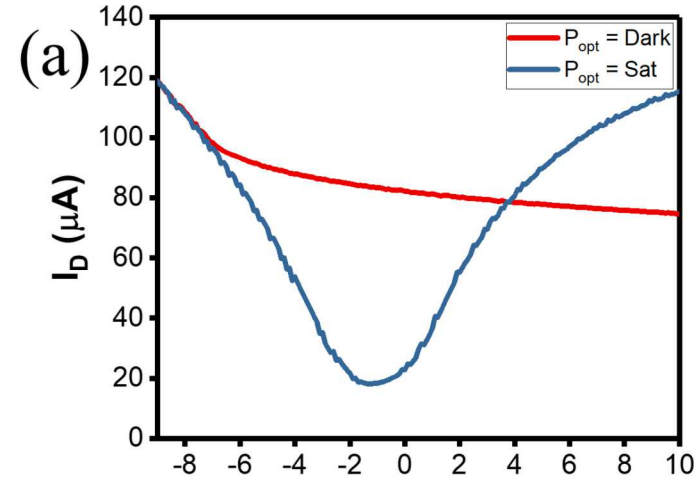
Interface charge is quenched between 77K - 250K

No generated dark current

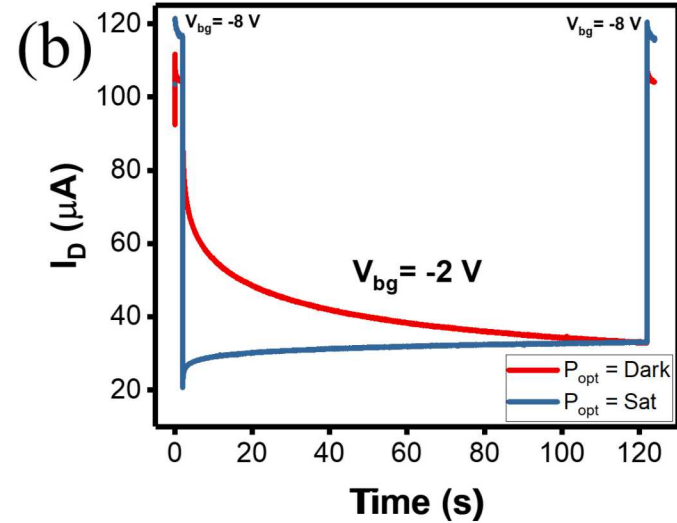


Reduction in dark current results in almost a 2X increase in responsivity at 77K

Highly defective interface D²GOS junction at 77K



Unresponsive device becomes functional at 77K



Although the dark current is reduced it is not completely quenched.

How do we move the D²GOS beyond Silicon (Visible)?

Easy

Graphene is easily transferable to any substrate

GOS Junction/GFET is simple to fabricate on the most common semiconducting-dielectric substrates.

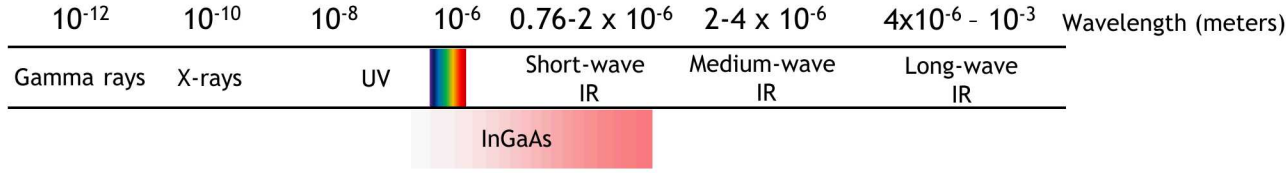
GOS structure must be depletable.

Hard

Semiconductor/Oxide interface must be of reasonably high quality.

Low doping concentration of semiconductor for large depletion width

Demonstration of D²GOS on InGaAs ($E_g \sim 0.76$ eV ($\sim 1.6 \mu\text{m}$))

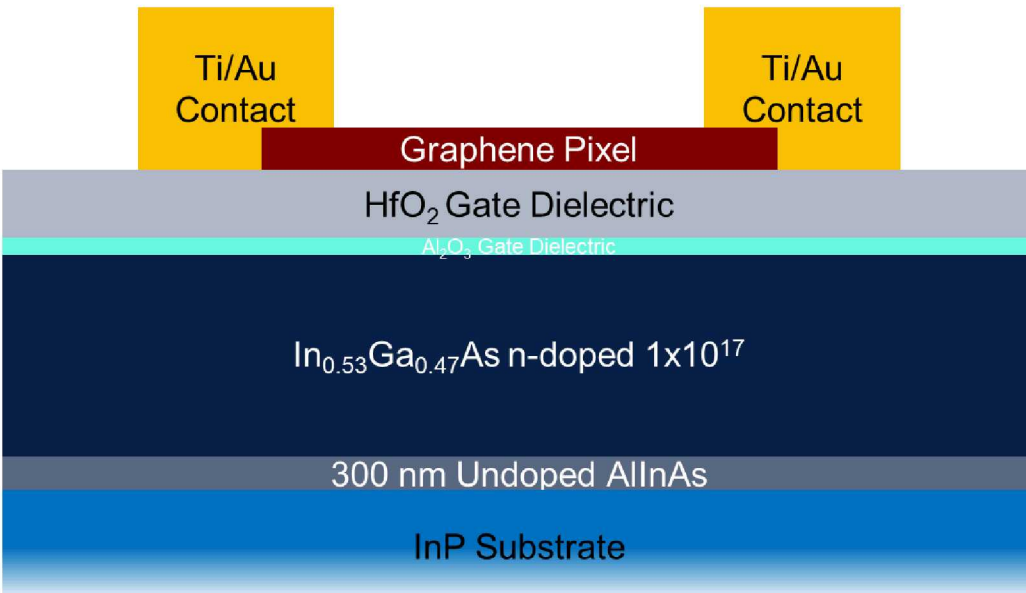


InGaAs Surface Preparation

Remove Native Oxide
BOE Etch 90 sec

Atomic Layer Deposition Recipe
300C N₂ Plasma 1 cycle
Al₂O₃ deposition 12 cycles (TMA)
HfO₂ Deposition 550 Cycles (TDMAH)

Anneal
N₂ gas anneal at 400 C for 15 min

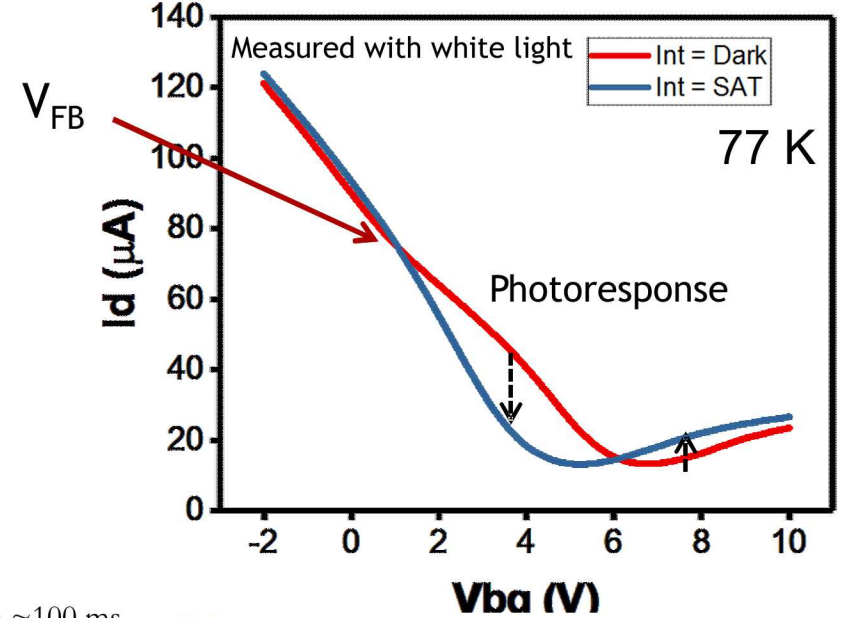


Dark Charge current quenched at 77K

Dark Current quenched up to 160K.

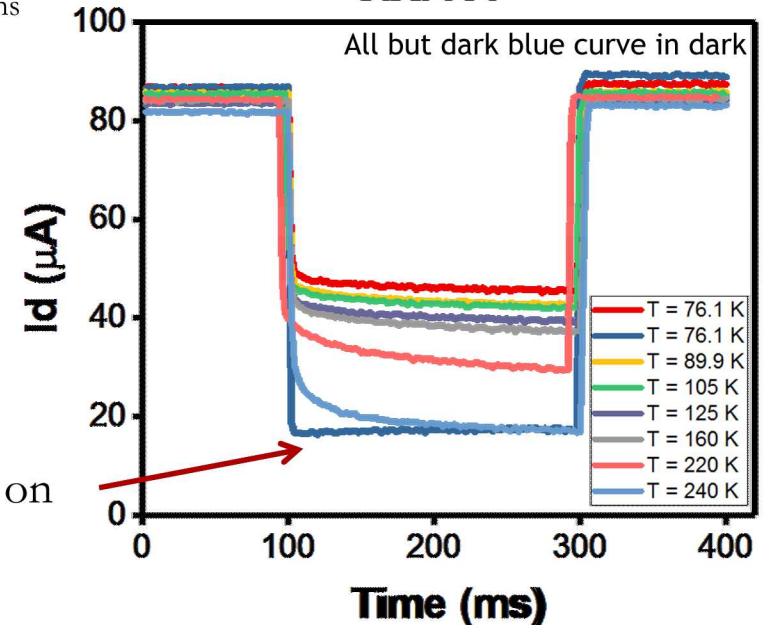
Device functional up to 240K but with ~ 100 ms well lifetime

Immediately saturates when illuminated

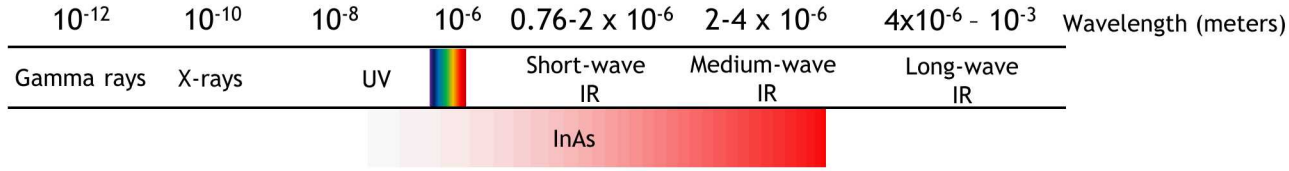


77K with light on

(Illuminated with White light)



Demonstration of D²GOS on InAs ($E_g \sim 0.35 \text{ eV}$ ($\sim 3.5 \text{ }\mu\text{m}$))



InAs Surface Preparation

Remove Native Oxide

BOE Etch 90 sec

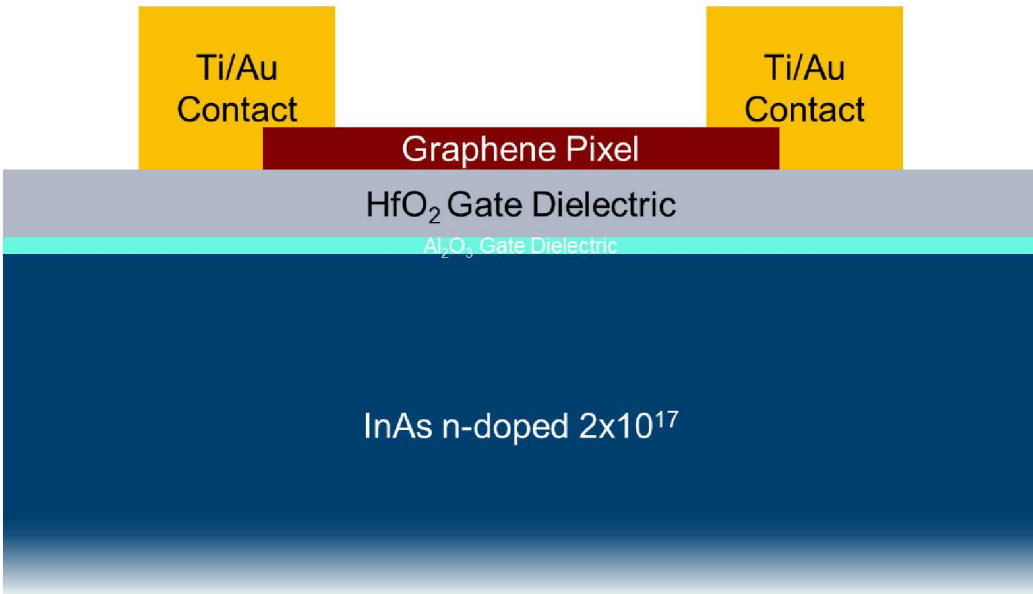
Surface Passivation

(NH₄)₂SO₄ soak for 5 min

Atomic Layer Deposition Recipe

Al₂O₃ deposition 10 cycles (TMA)

HfO₂ Deposition 550 Cycles (TDMAH)



Small photo response in depletion

Dark current appears quenched at 77K.

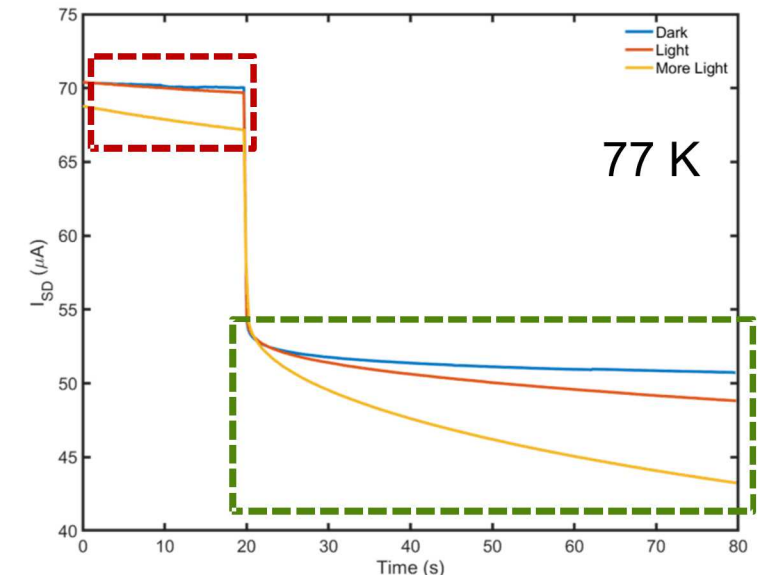
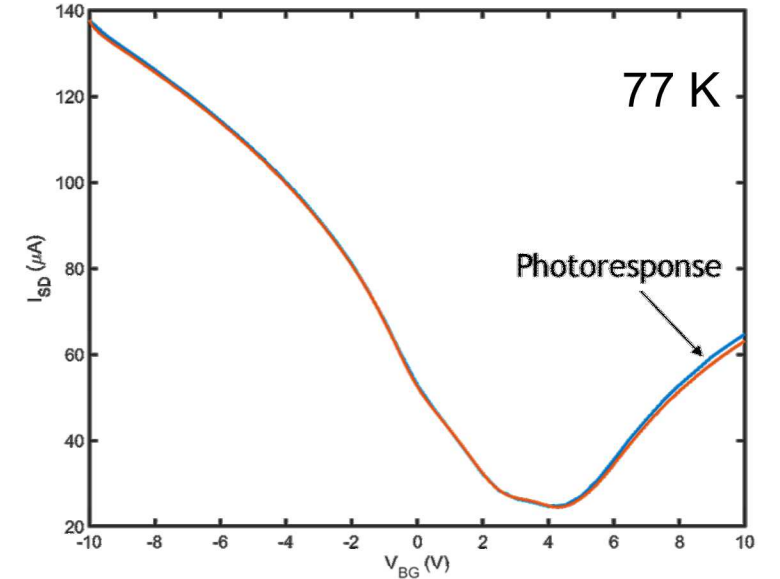
Responsive to light.

Photo Current proportional to incident light power.

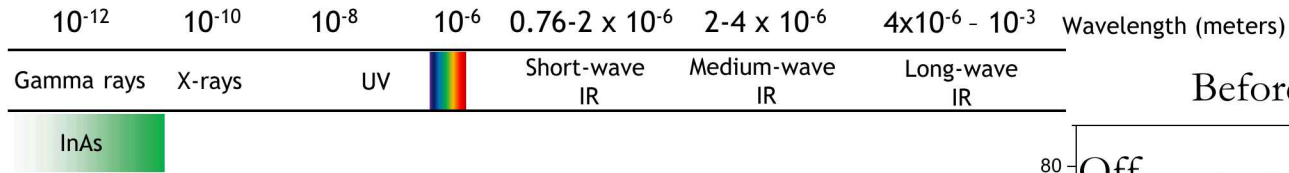
Current not saturating when flood illuminated (Si devices saturated immediately with powers low as 100 nW)

Some photo response in accumulation. Why?

(Illuminated with White light)



Silicon D²GOS for Gamma Ray Detection



Si D²GOS tested in Gammacell 220R

Cobalt 60 source

1.2 MeV

Sample lowered into Gammacell and exposed at 360°

Sample backgate pulsed at 0 V for 2 sec (Accumulation)
and then 10 V for 5 sec (Depletion)

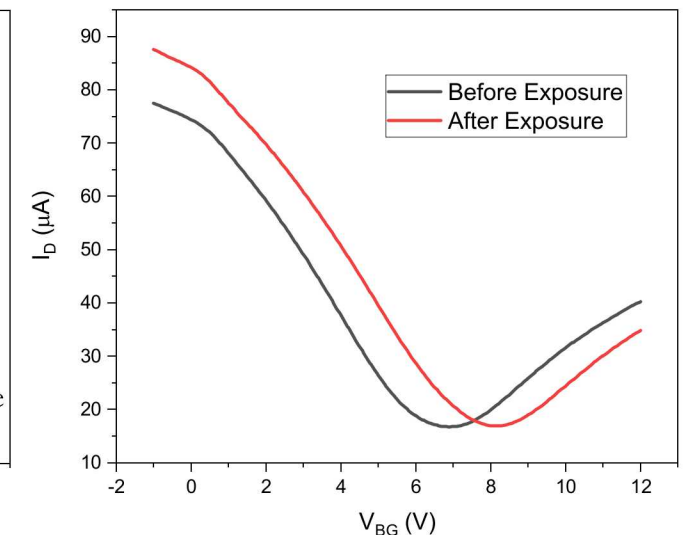
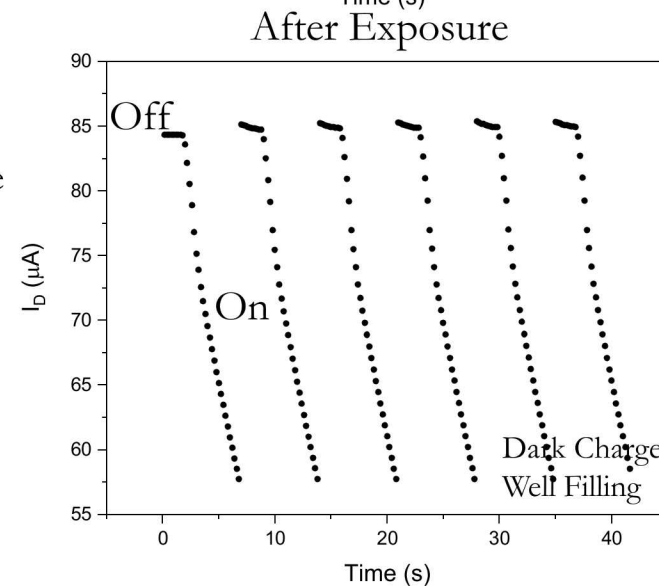
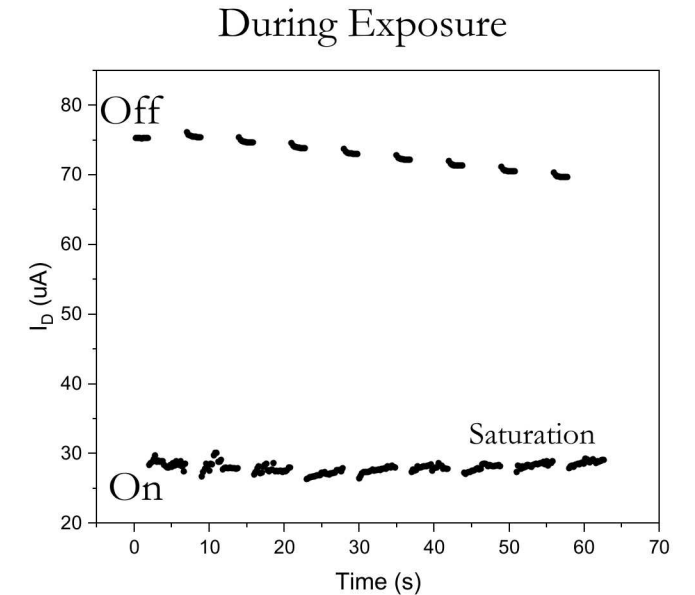
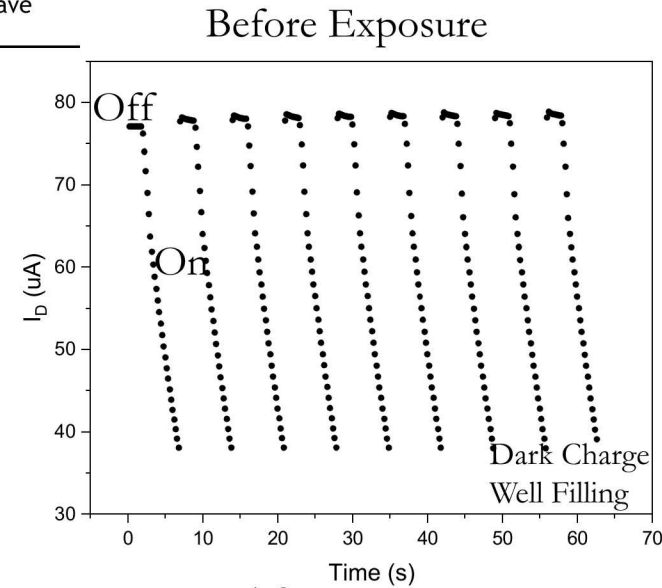
D²GOS Immediately Saturates when biased into deep depletion

Device not noticeably damaged from high energy gamma exposure

Gate leakage current increase was observed in during On state while
Being exposed to gamma radiation.

Returned to normal operation comparable to how it performed
before the exposure.

I-V curves showed slight shift but otherwise normal.



Demonstrated a path forward for optimizing D²GOS Detectors

- Improved Interface
- Improved Graphene Film

Demonstrated D²GOS on III-V Substrates

- Expanded detection into near and mid-wave IR

Detected 1.2 MeV Gamma Rays in Si D²GOS junction

- Device was not damaged
- Returned to normal operation after exposure

Michael D. Goldflam

Stephen W. Howell

Thomas E. Beechem III

Sean Smith

Joshua Shank

Bruce Draper

Raktim Sarma

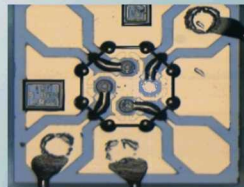
Anthony McDonald

SANDIA'S PHOTONIC MICROSYSTEMS

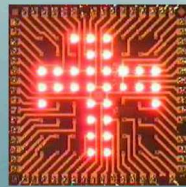
National Capabilities for Advanced Photonics R&D: design, model, fab, package, and test

Materials: Silicon, III-V (Phosphides, Arsenides, Antimonides, Nitrides), Lithium Niobate, Graphene, etc.

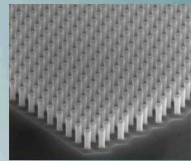
Sources



Single-Frequency Tunable VCSELs



High Efficiency VCSELs

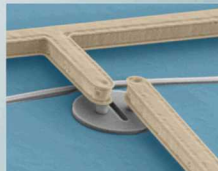


Nanowire Laser



High power GaAs laser

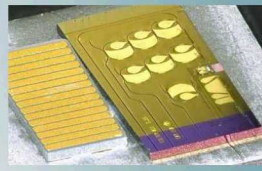
Control / Manipulation



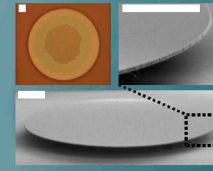
Resonant Optical Modulator/Filter



Array Waveguide Grating Channelizing Filter

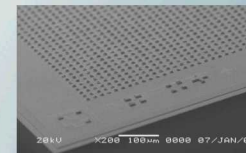


RF Channelizing Filter

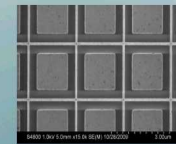


LiNbO3 Freq. Converter

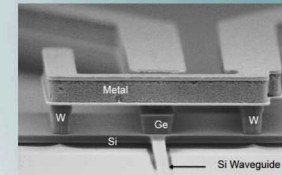
Detection



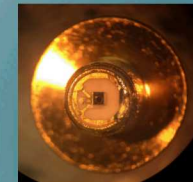
Infrared Detector



Plasmonic Perfect Absorber



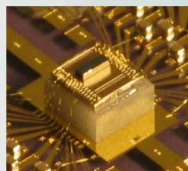
Germanium Detector on Silicon



X-ray Detector

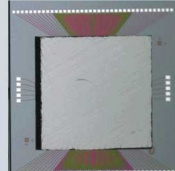
Heterogeneous Integration

III-V on CMOS

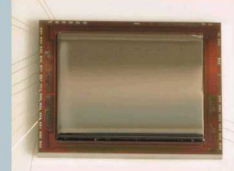


High-speed Optical Transceivers

CMOS on Si Photonics

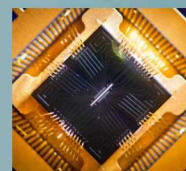


nBn on CMOS



IR Focal Plane Array w/ ROIC

Chip-scaled MicroSystems



Quantum Surface Ion Trap



Atomic Clock



Quantum Key Distribution Transceiver w/ microlenses



High-speed All-Optical Logic



Photovoltaics



Sandia National Laboratories

Learn about Photonics at Sandia:
National Security Photonics Center
sandia.gov/mstc/nspc

Sandia's Microsystems and Engineering Sciences Applications (MESA) for silicon photonics, III-V photonics, CMOS, and compound-semiconductor device fabrication, and heterogeneous integration



Avalanche Photodetector



QKD Transceiver



AWG RF Channelizer



IR FPA with ROIC



Photovoltaics w/microlenses



3-D Metamaterials



III-V on Silicon Optical Amplifier

Collaborate with us!

Visit us:

- On-line: sandia.gov/mesa/nspc

Email contact:

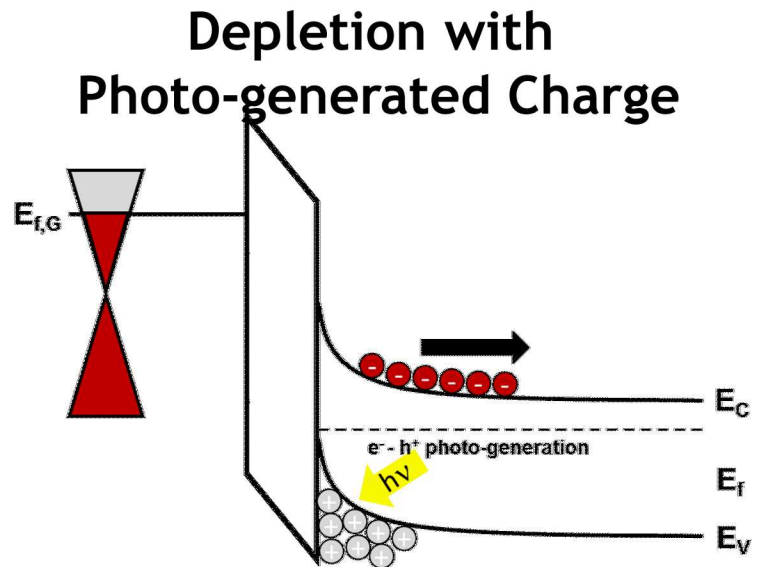
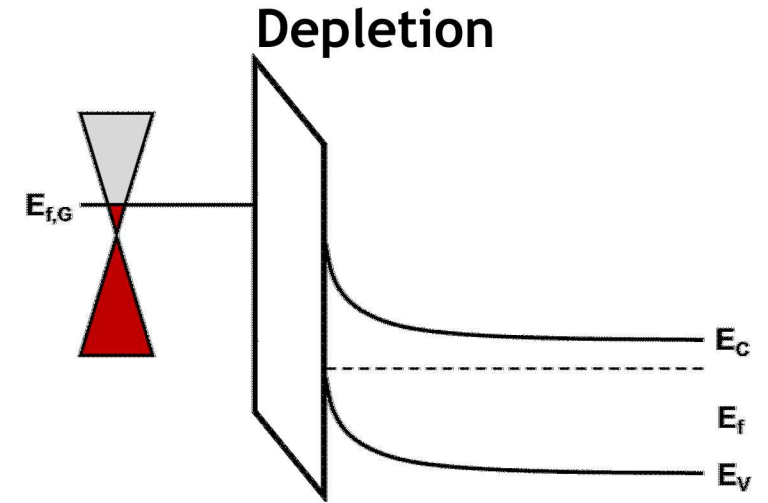
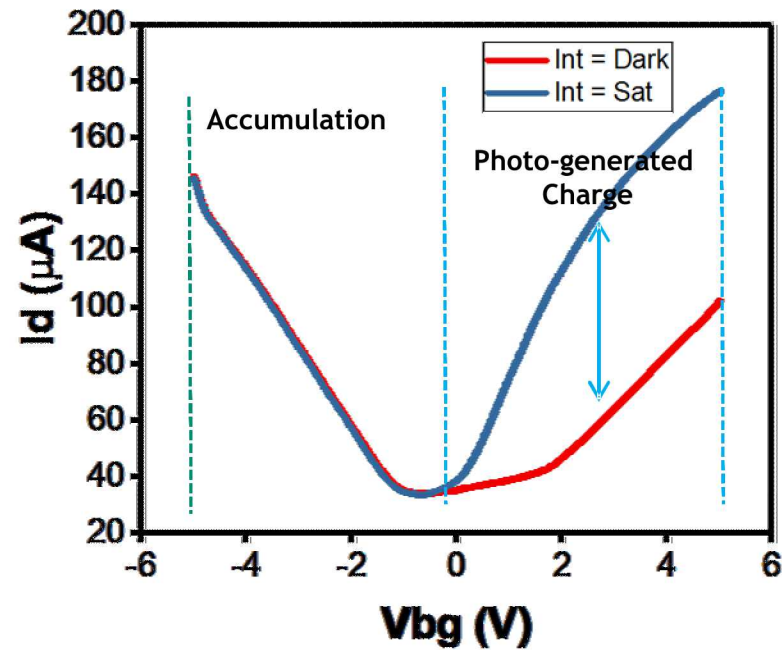
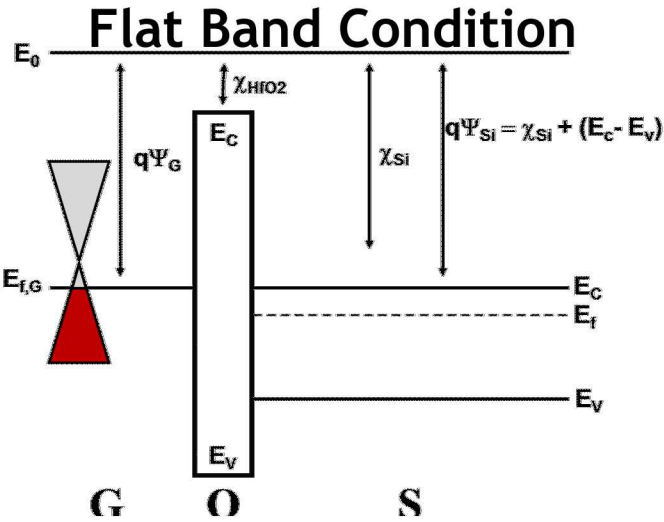
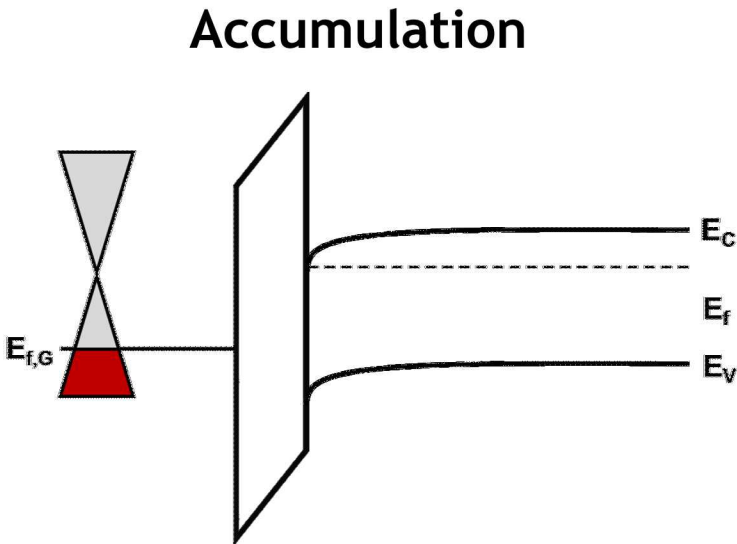
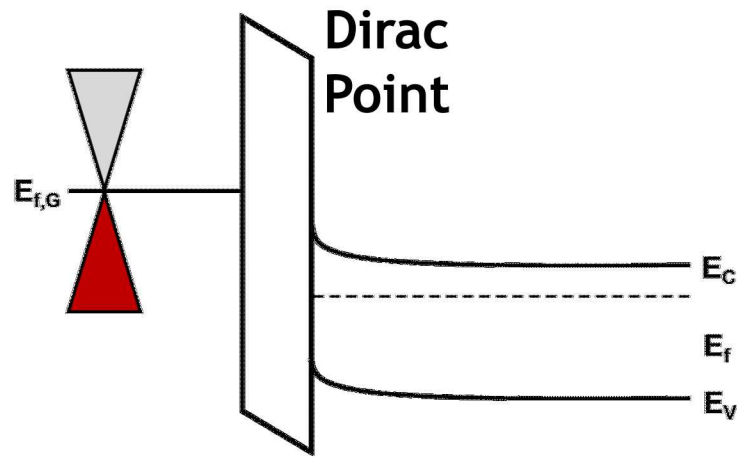
- photonics@sandia.gov

Career Opportunities for staff and students:

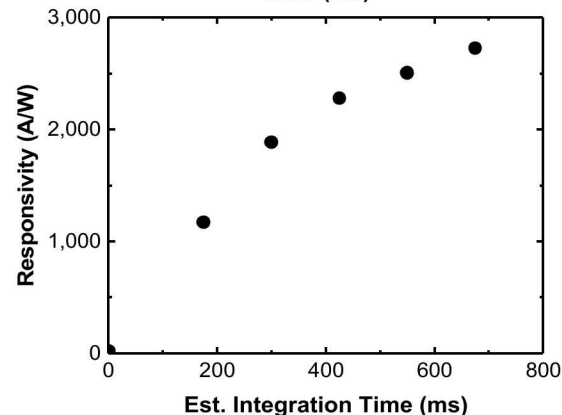
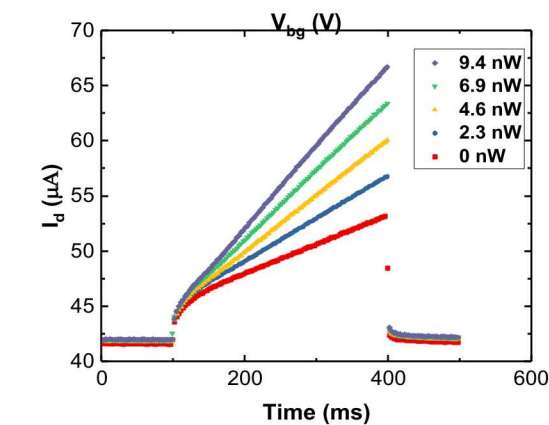
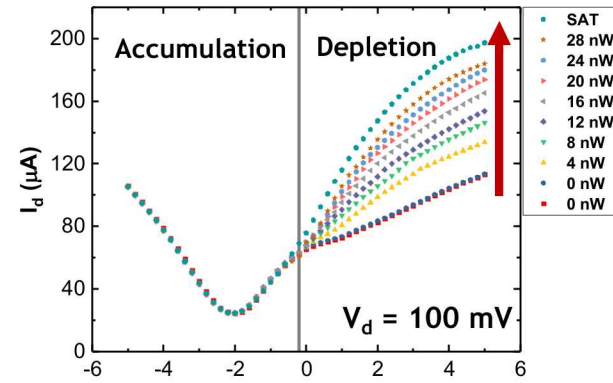
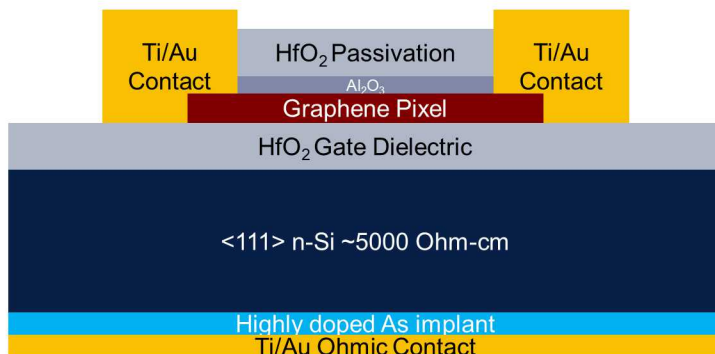
- www.sandia.gov/careers
 - Postdoc
 - Staff
 - Student interns (year-round or summer)

I will be happy to take any questions.

Band Diagram of "intrinsic" graphene D2GOS Junction Detector



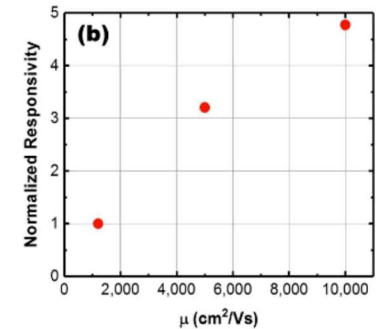
- Fabricated on low doped n-doped silicon for absorption in the visible regime.
- Graphene was slightly n-doped, close to intrinsic.
- Demonstrated nW sensitivity.
- High Responsivity
 - > 2500 A/W



Devices were functional but nowhere near optimized.

Problems

- Poor interface between Si and HfO₂.
 - 111 surface forms bad interface.
 - Potential well fills up quickly (~8 sec)
 - Thermally generated dark charge.
- Graphene mobility ~ 1200 cm²/s.
 - Near low end of CVD graphene quality

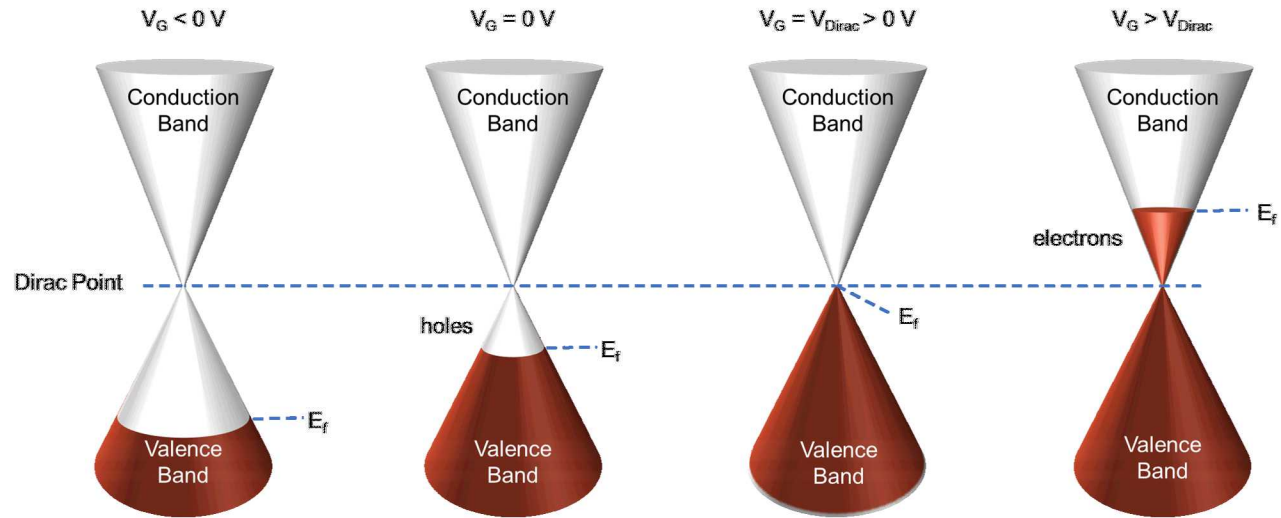


Only one of several possible configurations.

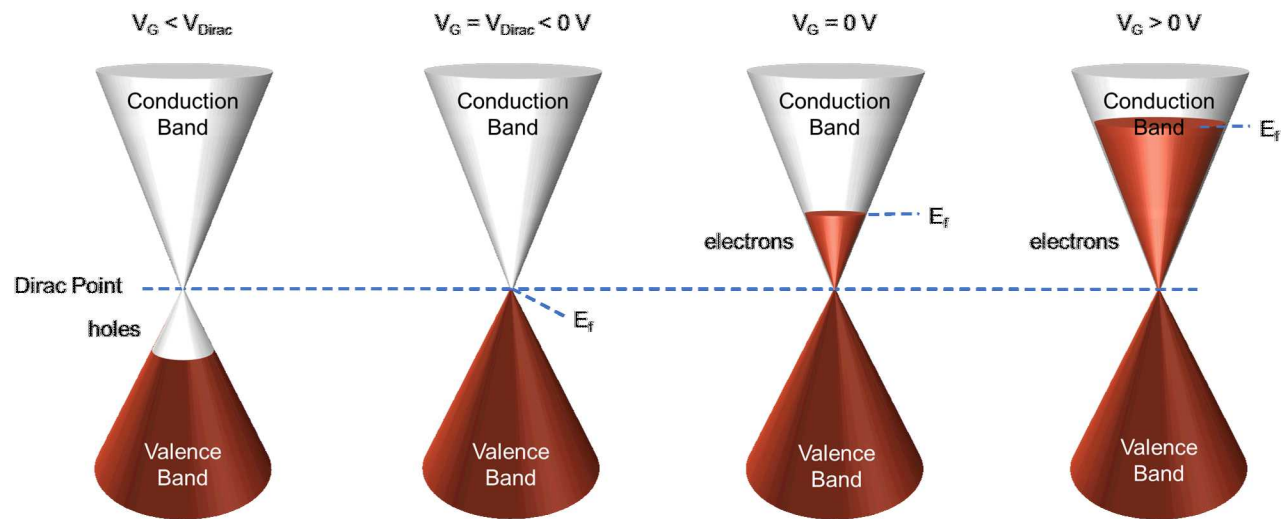
- N-doped Si
- N-doped Graphene

Graphene is Doped

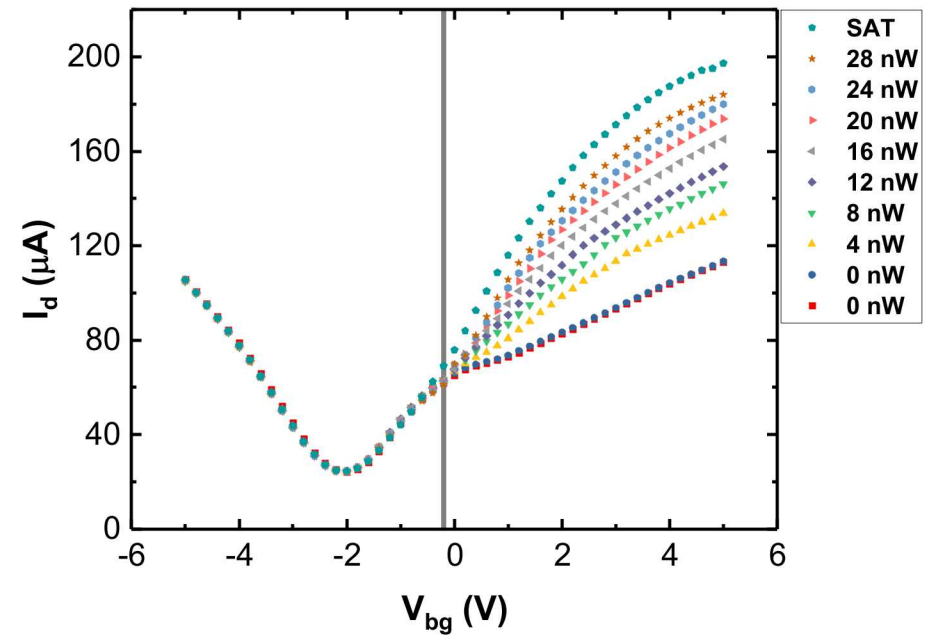
p-doped Graphene



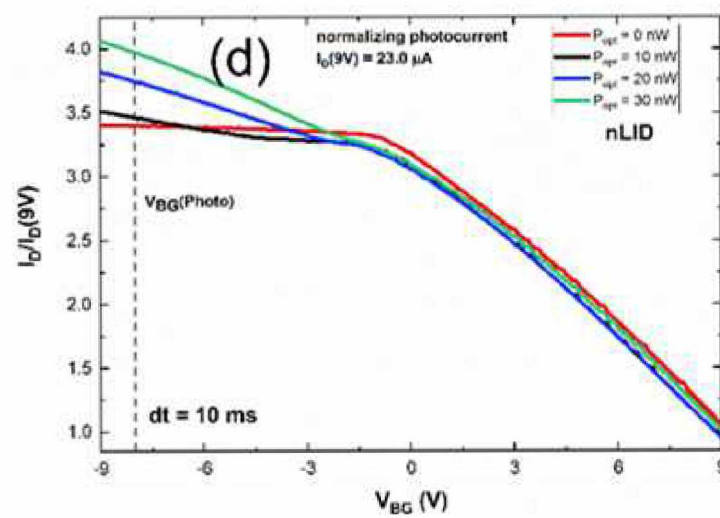
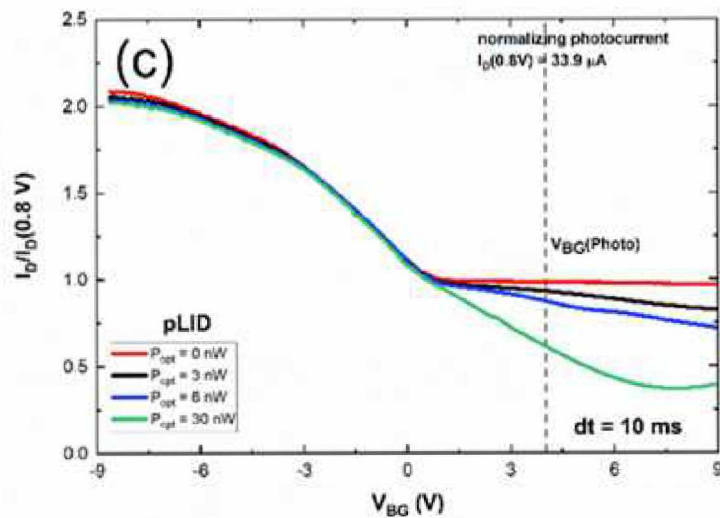
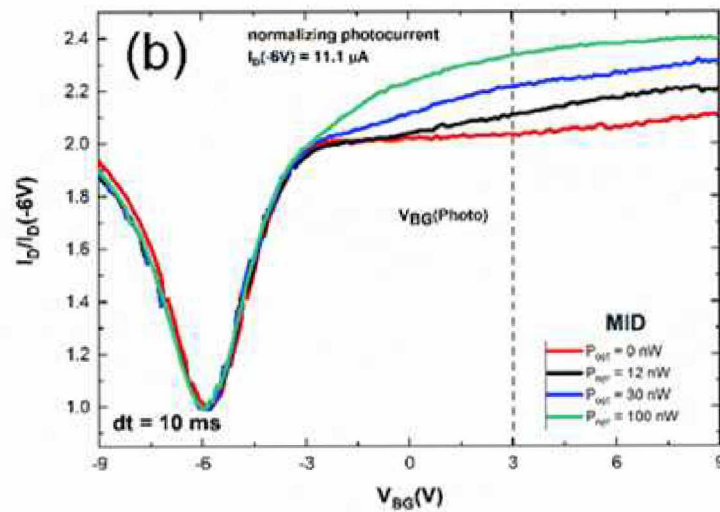
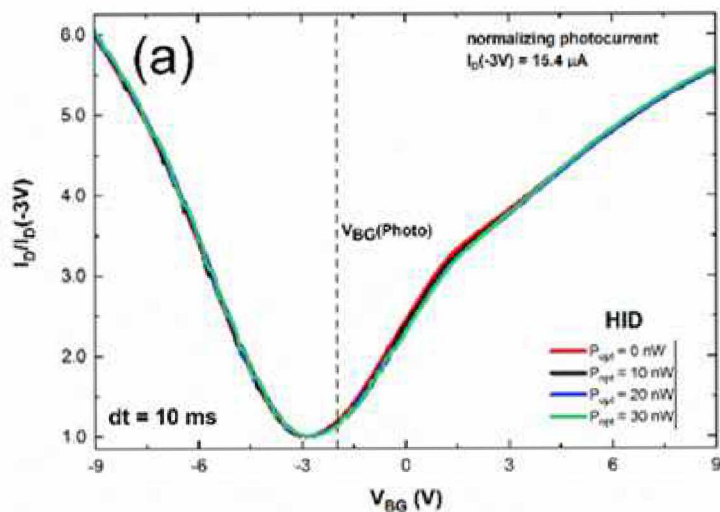
n-doped Graphene



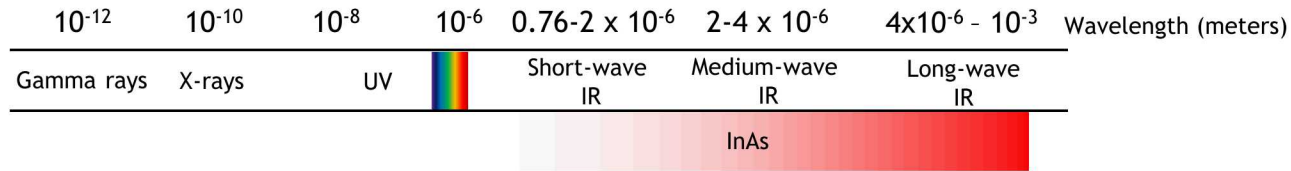
- First Generation Devices were n-doped Graphene on n-Si.
- This provided very predictable, easy to understand $I_d(V_{\text{bg}})$ curves.



$I_D(V_{BG})$ of HID, MID, p-LID and n-LID



Demonstration of D²GOS Junction of InSb ($E_g \sim 0.17 \text{ eV}$ ($\sim 7.3 \mu\text{m}$))



InSb Surface Preparation

Remove Native Oxide
BOE Etch 90 sec

Surface Passivation
(NH₄)₂SO₄ soak for 5 min

Atomic Layer Deposition Recipe
Al₂O₃ deposition 10 cycles (TMA)
HfO₂ Deposition 550 Cycles (TDMAH)

Small photo response in depletion

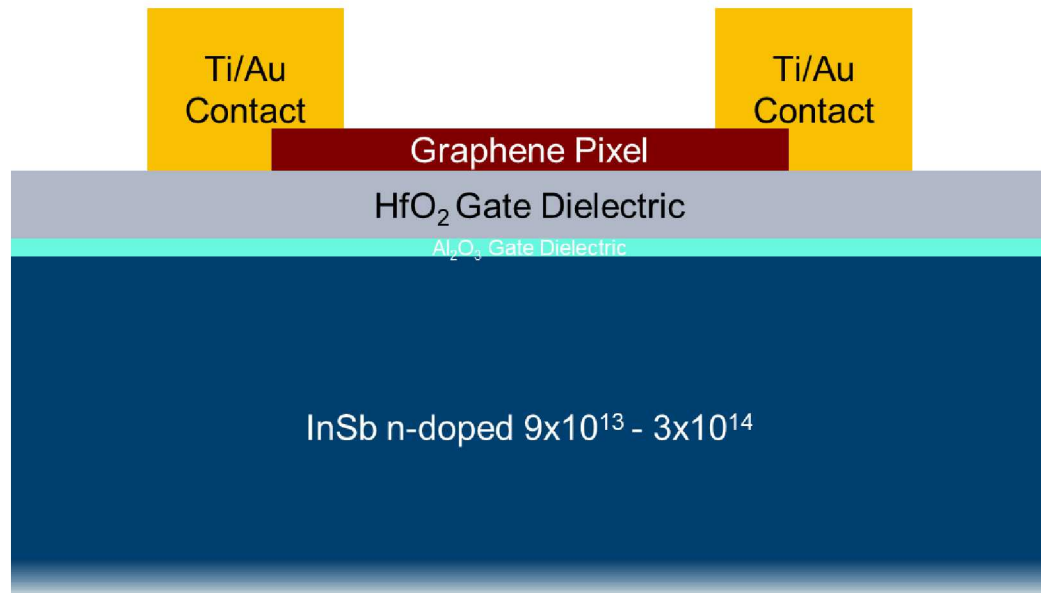
Dark current appears quenched at 77K.

Responsive to light.

Photo Current proportional to incident light power.

Current not saturating when flood illuminated (Si devices saturated immediately with powers low as 100 nW)

Some photo response in accumulation.
Why?



(Illuminated with White light)